

8 Amp Ultra Low Forward Voltage Schottky Rectifier

LSM835J-LSM845Je3
LSM835G-LSM845Ge3



Product Overview

The LSM8xx series provides a 8 Amp, Schottky surface mount rectifier with low forward voltage and low leakage current. The SMCJ J-bend design in the DO-214AB package allows for greater PC board mounting density. The SMCG Gull-wing design in the DO-215AB package is ideal for visible solder connections. For critical applications requiring very fast switching, these very low forward voltage Schottkys with their “hot carrier” features provide extremely fast switching to replace conventional ultrafast rectifiers.

Features

- Schottky Barrier Rectifier
- Surface Mount Plastic Package
- Guard Ring for Reverse Protection
- 150 °C Junction Temperature
- High Surge Capability
- Ultra Low Forward Voltage
- Schottky OR'ing diode
- RoHS compliant versions are available with an e3 suffix
- Moisture classification is a level 1 with no dry pack required per IPC/JEDEC J-STD-020F

Figure 1. DO-215AB (SMCG) Package

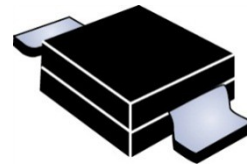


Figure 2. DO-214AB (SMCJ) Package



Applications/Benefits

- Silicon Schottky (hot carrier) rectifier for minimal t_{rr} and elimination of reverse-recovery oscillations to reduce need for EMI filtering
- For use in high-frequency switching power supplies, inverters, freewheeling, polarity protection, or “OR’ing” applications
- Low forward power loss and high efficiency

Note: All SMC series are equivalent to prior SMM package identifications.

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1. Maximum Ratings

Table 1-1. Maximum Ratings at 25 °C Unless Otherwise Noted

Parameters/Test Conditions	Symbol	Value	Unit
Storage Temperature	T_{STG}	-55 to +150	°C
Junction Temperature	T_J	-55 to +150	°C
Thermal Resistance Junction-to-Lead	$R_{\theta JL}$	20	°C/W
Forward Surge Current ¹	I_{FSM}	350	A
Average Rectified Forward Current (Square Wave)	I_O	8.0	A
Solder Temperature at 10 s	—	260	°C

Note:

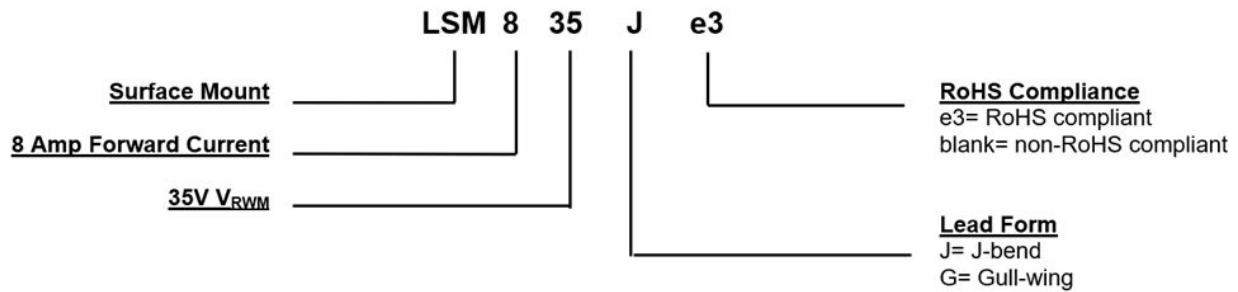
- At 8.3 ms single half-sine waveform superimposed on rated load (JEDEC method), $T_J = 150\text{ °C}$.

1.1. Mechanical and Packaging

- Case: Void-free transfer molded thermosetting epoxy body meeting UL94V-0
- Terminals: Tin-lead or RoHS compliant annealed matte-tin plating, readily solderable per MIL-STD-750, method 2026
- Polarity: Indicated by cathode band
- Tape-and-Reel: Standard per EIA-481-B (add "TR" suffix to part number). Consult factory for quantities.
- Weight: Approximately 0.13 grams
- See Package Dimensions

2. Part Nomenclature

Figure 2-1. Part Nomenclature



2.1. Symbols and Definitions

Table 2-1. Symbols and Definitions

Symbol	Definition
C_J	Junction Capacitance: The total small signal capacitance between the diode terminals of a complete device.
I_F	Forward Current: The forward current dc value, no alternating component.
I_{FSM}	Maximum Forward Surge Current: The forward current, surge peak or rated forward surge current.
I_O	Average Rectified Forward Current: The current average over a full cycle with a 180 degree conduction angle (square wave).
I_R	Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.
V_F	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.
V_R	Reverse Voltage: The reverse voltage dc value, no alternating component.
V_{RRM}	Repetitive Peak Reverse Voltage: The peak reverse voltage including all repetitive transient voltages but excluding all non-repetitive transient voltages.
V_{RWM}	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range excluding all transient voltages (ref JESD282-B). Also sometimes known as PIV.

3. Electrical Characteristics

Table 3-1. Electrical Characteristics at 25 °C Unless Otherwise Stated

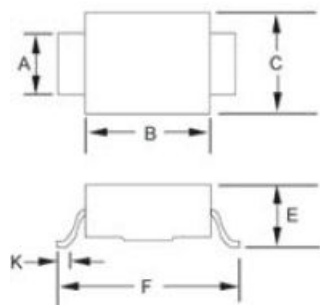
Part Number	Device Marking	Working Peak Reverse Voltage V_{RWM} Volts	Reverse Current I_R $T_J = 25\text{ °C}$ at V_{RWM} mA	Peak Forward Voltage ¹ V_F at 8A $T_J = 25\text{ °C}$ V_{FM} Volts	Peak Forward Voltage ¹ V_F at 8A $T_J = 150\text{ °C}$ V_{FM} Volts	Junction Capacitance at 5V C_J pF
		MAX	MAX	MAX	MAX	Typical
LSM835(G/J)(e3)	L835	35	2	0.52	0.40	575
LSM840(G/J)(e3)	L840	40	2	0.52	0.40	575
LSM845(G/J)(e3)	L845	45	2	0.52	0.40	575

Note:

1. Obtained through square wave pulse with a pulse width of 300 μ s and a 2% duty cycle.

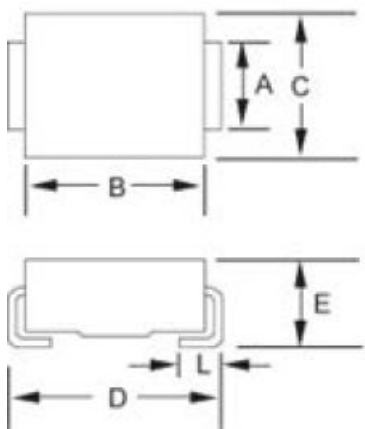
4. Package Dimensions

Figure 4-1. SMCG (DO-215AB)



Ltr	Dimensions			
	Inch		Millimeters	
	Min	Max	Min	Max
A	0.117	0.123	2.97	3.12
B	0.260	0.280	6.60	7.11
C	0.220	0.245	5.59	6.22
E	0.075	0.095	1.91	2.41
F	0.380	0.400	9.65	10.16
K	0.025	0.040	0.640	1.02

Figure 4-2. SMCJ (DO-214AB)



Ltr	Dimensions			
	Inch		Millimeter	
	Min	Max	Min	Max
A	0.117	0.123	2.97	3.12
B	0.260	0.280	6.60	7.11
C	0.220	0.245	5.59	6.22
D	0.307	0.322	7.80	8.18
E	0.075	0.095	1.91	2.41
L	0.030	0.060	0.760	1.52

5. Pad Layout

Figure 5-1. Pad Layout

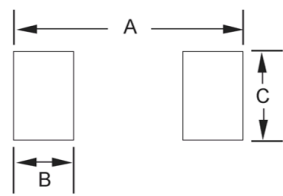


Table 5-1. SMCG (DO-215AB)

Ltr	Inch	Millimeters
A	0.510	12.95
B	0.110	2.79
C	0.150	3.81

Table 5-2. SMCJ (DO-214AB)

Ltr	Inch	Millimeter
A	0.390	9.90
B	0.110	2.79
C	0.150	3.81

6. Revision History

Revision	Date	Description
A	08/2025	Initial version

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ISBN: 979-8-3371-1758-4

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